Data Management Plan (DMP) 1,2

Instructions: Respond to each of the requirements with concise language. Do not include detailed methodology. Each DMP will be reviewed during award negotiations and uploaded to the Defense Technical Information Center following approval. Do not include proprietary information. DMPs should be no more than two pages. Ensure text responses fit within the maximum character limit per field.

1.Type of data, software, or other materials to be produced: 2. Description of how the data will be acquired 3. Description of the time and location of data acquisition (if scientifically relevant) 4. Description of how the data will be processed	Log Number:	Principal Investigator (PI):
2. Description of how the data will be acquired 3. Description of the time and location of data acquisition (if scientifically relevant)		
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5. Description of file formats of data and naming conventions		
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6. Description of quality assurance and control measures (during collection, processing, and analyses)	
7. Description of dataset (when existing data resources are used only)	
8. Description of data standards and metadata standards to be used (format and content)	
9. Description of time frame for preservation of data	
10. Distribution of Data/Limitations to Sharing Data	

¹The plan may consider the balance between the relative value of data preservation and other factors, such as the associated cost and administrative burden. The plan will provide a justification for such decisions. *Include a statement that the data cannot be made available to the public when there are controlled unclassified information concerns* (e.g. "This data cannot be cleared for public release in accordance with the requirements in DoDI 5230.09").

² For partnering awards with an Initiating PI and partnering PI(s), each award must submit a separate DMP.

PLEASE NOTE: This document is meant to provide a suggested Data Management Plan (DMP) format preferred by the Congressionally Directed Medical Research Programs (CDMRP). As described in Enclosure 3, Section 3.c. in DoDI 3200.12, the DoD Scientific and Technical Information Program (STIP), the Department of Defense requires specific elements to be included within the DMP. Due to differences in requirements, awardees should not upload a copy of the NIH Data Management and Sharing Plan. The DoD sustains a coordinated program to manage scientific and technical information created or acquired in the execution of research and engineering activities. A DMP is different than a Data and Research Resources Sharing Plan; therefore do not duplicate the Data and Research Resources Sharing Plan.

The CDMRP is committed to data integrity and the intellectual property rights of awardees. **Do not include proprietary information**.

References:

- 1. Enclosure 3, Section 3.c. in DoDI 3200.12
- 2. General Application Instructions, Appendix 7 Section F.
- 3. DoDI 5230.09